Time	Number	Title (in English)	**Name**	School.
9:45-10:00	O-1	Wafer Bonding Innovation with ALD metal oxide for Next-Generation 3D Integration	Hayato Kitagawa	Yokohama National University
10:00-10:15	O-2	Evaluation of PI Surface Treatments for Reliable Hybrid Bonding	Heng-Ching, Mie	National Cheng Kung University
10:15-10:30	O-3	Investigating Copper oxide stability in TCB Cu-Cu bonding	Kun-Yuan Zeng	National Cheng Kung University
10:30-10:45	O-4	Radical-Induced Surface Activation Enabling Plasma-Free Fine-Pitch Hybrid Bonding of SiCN/Cu	Bungo Tanaka	Tohoku University
10:45-11:00	O-5	Operational Control of High-Speed Switching Valves for On-Demand Delivery of Precursors in ALD	Ishida Kanta	Kumamoto University
11:10-11:25	O-6	Light-removable surface protective layer for Cu to Cu bonding applications	Chieh-Ling Hsu	National Chung Hsing University
11:25-11:40	O-7	Electric Current–Induced Phase Stability in Ni-Stabilized η-Cu_6Sn_5 Intermetallics	Shubhayan Mukherjee	National Cheng Kung University
11:40-11:55	O-8	An Electromigration Study of Novel 3D Cu Microvia Interconnects for Advanced High-density Fan-out Packaging	Yi-Chen Keng	National Taiwan University of Science and Technology
11:55-11:10	O-9	Effect of Residual Stress in Cu Substrate on Cu-to-Cu Bonding Properties	Li-Chen Wu	National Central University
11:10-12:25	O-10	Electrochemical co-deposition of Cu–Ag foils for application in Cu–Cu thermocompression bonding	Yu-Ju Li	National Chung Hsing University
13:40-13:55	O-11	Die-level Via-last TSV Formation for 3D-IC Prototyping from Multi-Project Wafers	Jiayi Shen	Tohoku university
13:55-14:10	O-12	Electromigration of FCQFN Ag-plated Cu Pillar Solder Interconnects for High-power Automotive Packaging: Effects of Ni Metallization on Interfacial Reaction and Electrical Performance	Meng-Chun Chiu	National Taiwan University of Science and Technology
14:10-14:25	O-13	Modeling electromigration-induced resistance change in Sn-58Bi Solder Using Machine Learning Approach	Chi Chen	National Cheng Kung University
14:25-14:40	O-14	Enhancing Al–Al Ultrasonic Bonding via VUV-Induced Surface Modification in Oxalic Acid Atmosphere	Yi-Jun, Hsiao	National Chung Hsing University
14:40-14:55	O-15	Green Laser Technologies for Semiconductor Fabrication Process	Vishnu Narayanan S.	National Tsing Hua University
15:05-15:20	O-16	A study on the growth kinetics and hardness of IMCs in Au-In joints	Chih-Chia Bill Chang	National Taiwan University

15:20-15:35	O-17	Development of High-temperature Lead-free solders: Zn-Sn-Al-Cu Based Alloy	Yu-Sheng Chen	National Taiwan University of Science and Technology
15:35-15:50	O-18	Influence of Minor Alloying Elements on the Properties of Sn-Bi Alloys	Yu-Hsin Lin	National Taiwan University
15:50-14:05	O-19	Development of a method for simultaneous measurement of saturated solubility and diffusion coefficient of organometallic compounds in high-temperature supercritical CO_2/H_2	Oda Shota	Kumamoto University
14:05-16:20	O-20	Design Sn-In-X low-temperature solder under machine learning guidance	Hao Wei Kuo	National Cheng Kung University